

# NX3008PBKMB

# 30 V, single P-channel Trench MOSFET Rev. 1 — 11 May 2012

Product data sheet

#### 1. **Product profile**

### 1.1 General description

P-channel enhancement mode Field-Effect Transistor (FET) in a leadless ultra small DFN1006B-3 (SOT883B) Surface-Mounted Device (SMD) plastic package using Trench MOSFET technology.

### 1.2 Features and benefits

- Very fast switching
- Low threshold voltage
- Trench MOSFET technology
- ESD protection up to 2 kV
- Ultra thin package profile with 0.37 mm height

### 1.3 Applications

- Relay driver
- High-speed line driver

- High-side loadswitch
- Switching circuits

#### 1.4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
$V_{DS}$	drain-source voltage	T <sub>j</sub> = 25 °C		-	-	-30	V
$V_{GS}$	gate-source voltage			-8	-	8	V
I <sub>D</sub>	drain current	$V_{GS}$ = -4.5 V; $T_{amb}$ = 25 °C	<u>[1]</u>	-	-	-300	mA
Static charact	eristics						
R <sub>DSon</sub>	drain-source on-state resistance	$V_{GS} = -4.5 \text{ V}; I_D = -200 \text{ mA}; T_j = 25 \text{ °C}$		-	2.8	4.1	Ω

<sup>[1]</sup> Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for drain 1 cm<sup>2</sup>.



### 2. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	G	gate		
2	S	source	1   3	D
3	D	drain	Transparent top view  SOT883B (DFN1006B-3)	G S 017aaa259

### 3. Ordering information

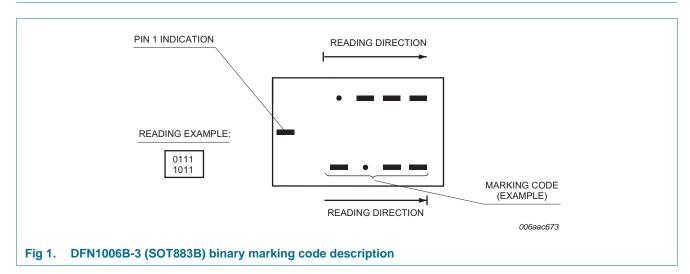
Table 3. Ordering information

Type number	Package					
	Name	Description	Version			
NX3008PBKMB	DFN1006B-3	Leadless ultra small plastic package; 3 solder lands; body $1.0 \times 0.6 \times 0.37$ mm	SOT883B			

### 4. Marking

Table 4. Marking codes

Type number	Marking code
NX3008PBKMB	0000 0100



### 5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
$V_{DS}$	drain-source voltage	T <sub>j</sub> = 25 °C		-	-30	V
V <sub>GS</sub>	gate-source voltage			-8	8	V
I <sub>D</sub>	drain current	V <sub>GS</sub> = -4.5 V; T <sub>amb</sub> = 25 °C	<u>[1]</u>	-	-300	mA
		V <sub>GS</sub> = -4.5 V; T <sub>amb</sub> = 100 °C	<u>[1]</u>	-	-185	mA
I <sub>DM</sub>	peak drain current	T <sub>amb</sub> = 25 °C; single pulse; t <sub>p</sub> ≤ 10 μs		-	-1.2	Α
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> = 25 °C	[2]	-	360	mW
			<u>[1]</u>	-	715	mW
		T <sub>sp</sub> = 25 °C		-	2700	mW
Tj	junction temperature			-55	150	°C
T <sub>amb</sub>	ambient temperature			-55	150	°C
T <sub>stg</sub>	storage temperature			-65	150	°C
Source-drai	n diode					
Is	source current	T <sub>amb</sub> = 25 °C	<u>[1]</u>	-	-300	mA
ESD maxim	um rating					
V <sub>ESD</sub>	electrostatic discharge voltage	НВМ	[3]	-	2000	V

- [1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for drain 1 cm<sup>2</sup>.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [3] Measured between all pins.

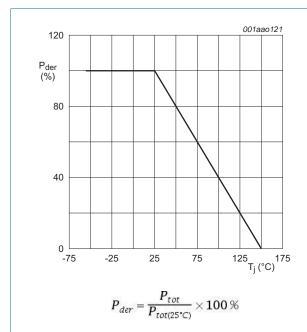


Fig 2. Normalized total power dissipation as a function of junction temperature

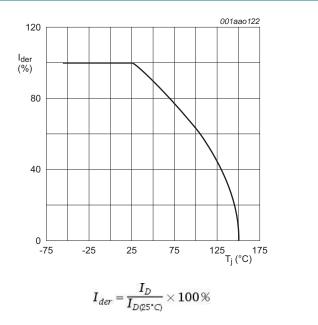
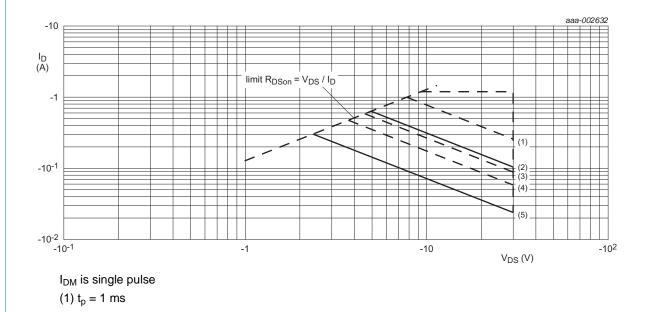


Fig 3. Normalized continuous drain current as a function of junction temperature

NX3008PBKMB

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- (2) DC;  $T_{sp} = 25 \, ^{\circ}\text{C}$
- (3)  $t_p = 10 \text{ ms}$
- (4)  $t_p = 100 \text{ ms}$
- (5) DC;  $T_{amb} = 25$  °C; drain mounting pad 1 cm<sup>2</sup>

Fig 4. Safe operating area; junction to ambient; continuous and peak drain currents as a function of drain-source voltage

### 6. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	<u>[1]</u>	-	305	360	K/W
			[2]	-	150	175	K/W
R <sub>th(j-sp)</sub>	thermal resistance from junction to solder point			-	-	40	K/W

- [1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for drain 1 cm<sup>2</sup>.

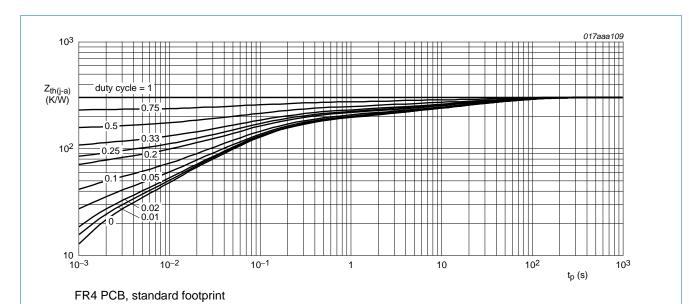


Fig 5. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

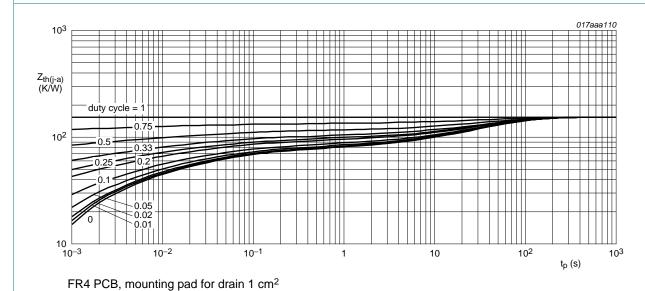


Fig 6. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

### 7. Characteristics

Table 7. Characteristics

Parameter	Conditions	Min	Тур	Max	Unit
aracteristics					
drain-source breakdown voltage	$I_D = -250 \mu A; V_{GS} = 0 V; T_j = 25 °C$	-30	-	-	V
gate-source threshold voltage	$I_D = -250 \ \mu A; \ V_{DS} = V_{GS}; \ T_j = 25 \ ^{\circ}C$	-0.6	-0.9	-1.1	V
drain leakage current	$V_{DS} = -30 \text{ V}; V_{GS} = 0 \text{ V}; T_j = 150 \text{ °C}$	-	-	-10	μΑ
	$V_{DS} = -30 \text{ V}; V_{GS} = 0 \text{ V}; T_j = 25 \text{ °C}$	-	-	-1	μΑ
gate leakage current	$V_{GS} = 8 \text{ V}; V_{DS} = 0 \text{ V}; T_j = 25 ^{\circ}\text{C}$	-	-0.2	-1	μA
	$V_{GS} = -8 \text{ V}; V_{DS} = 0 \text{ V}; T_j = 25 \text{ °C}$	-	-0.2	-1	μΑ
	$V_{GS} = 4.5 \text{ V}; V_{DS} = 0 \text{ V}; T_j = 25 \text{ °C}$	-	-10	-	nA
	$V_{GS} = -4.5 \text{ V}; V_{DS} = 0 \text{ V}; T_j = 25 \text{ °C}$	-	-10	-	nA
	$V_{GS} = 2.5 \text{ V}; V_{DS} = 0 \text{ V}; T_j = 25 \text{ °C}$	-	-1	-	nA
	$V_{GS} = -2.5 \text{ V}; V_{DS} = 0 \text{ V}; T_j = 25 \text{ °C}$	-	-1	-	nA
drain-source on-state	$V_{GS} = -4.5 \text{ V}; I_D = -200 \text{ mA}; T_j = 25 \text{ °C}$	-	2.8	4.1	Ω
resistance	$V_{GS}$ = -4.5 V; $I_{D}$ = -200 mA; $T_{j}$ = 150 °C	-	5.3	7.8	Ω
	$V_{GS} = -2.5 \text{ V}; I_D = -10 \text{ mA}; T_j = 25 \text{ °C}$	-	5.3	6.5	Ω
forward transconductance	$V_{DS} = -10 \text{ V}; I_D = -200 \text{ mA}; T_j = 25 \text{ °C}$	-	160	-	mS
characteristics					
total gate charge	$V_{DS} = -15 \text{ V}; I_D = -200 \text{ mA};$	-	0.55	0.72	nC
gate-source charge	$V_{GS} = -4.5 \text{ V}; T_j = 25 \text{ °C}$	-	0.23	-	nC
gate-drain charge		-	0.09	-	nC
input capacitance	$V_{DS} = -15 \text{ V}; f = 1 \text{ MHz}; V_{GS} = 0 \text{ V};$	-	31	46	pF
output capacitance	T <sub>j</sub> = 25 °C	-	6.5	-	pF
reverse transfer capacitance		-	2.3	-	pF
turn-on delay time	$V_{DS}$ = -20 V; $R_L$ = 250 $\Omega$ ; $V_{GS}$ = -4.5 V;	-	19	38	ns
rise time	$R_{G(ext)} = 6 \Omega; T_j = 25 °C$	-	30	-	ns
turn-off delay time		-	65	130	ns
fall time		-	38	-	ns
rain diode					
source-drain voltage	$I_S = -200 \text{ mA}; V_{GS} = 0 \text{ V}; T_j = 25 \text{ °C}$	-0.47	-0.88	-1.2	V
	drain-source breakdown voltage gate-source threshold voltage drain leakage current gate leakage current gate leakage current drain-source on-state resistance forward transconductance characteristics total gate charge gate-source charge gate-drain charge input capacitance output capacitance reverse transfer capacitance turn-on delay time rise time turn-off delay time fall time rain diode	drain-source breakdown voltage $ \begin{array}{l} \text{drain-source} \\ \text{breakdown voltage} \\ \text{gate-source threshold} \\ \text{voltage} \\ \\ \text{drain leakage current} \\ \\ \text{VDS} = -30 \text{ V; V}_{DS} = \text{V}_{GS}; T_j = 25 \text{ °C} \\ \\ \text{VDS} = -30 \text{ V; V}_{GS} = 0 \text{ V; T}_j = 150 \text{ °C} \\ \\ \text{VDS} = -30 \text{ V; V}_{GS} = 0 \text{ V; T}_j = 25 \text{ °C} \\ \\ \text{VDS} = -30 \text{ V; V}_{DS} = 0 \text{ V; T}_j = 25 \text{ °C} \\ \\ \text{VDS} = -30 \text{ V; V}_{DS} = 0 \text{ V; T}_j = 25 \text{ °C} \\ \\ \text{VDS} = -30 \text{ V; V}_{DS} = 0 \text{ V; T}_j = 25 \text{ °C} \\ \\ \text{VDS} = -30 \text{ V; V}_{DS} = 0 \text{ V; T}_j = 25 \text{ °C} \\ \\ \text{VDS} = -4.5 \text{ V; VDS} = 0 \text{ V; T}_j = 25 \text{ °C} \\ \\ \text{VDS} = -4.5 \text{ V; VDS} = 0 \text{ V; T}_j = 25 \text{ °C} \\ \\ \text{VDS} = -2.5 \text{ V; VDS} = 0 \text{ V; T}_j = 25 \text{ °C} \\ \\ \text{VDS} = -2.5 \text{ V; VDS} = 0 \text{ V; T}_j = 25 \text{ °C} \\ \\ \text{VDS} = -2.5 \text{ V; VDS} = 0 \text{ V; T}_j = 25 \text{ °C} \\ \\ \text{VDS} = -4.5 \text{ V; ID} = -200 \text{ mA; T}_j = 25 \text{ °C} \\ \\ \text{VDS} = -4.5 \text{ V; ID} = -200 \text{ mA; T}_j = 25 \text{ °C} \\ \\ \text{VDS} = -10 \text{ V; ID} = -200 \text{ mA; T}_j = 25 \text{ °C} \\ \\ \text{VDS} = -10 \text{ V; ID} = -200 \text{ mA; T}_j = 25 \text{ °C} \\ \\ \text{VDS} = -10 \text{ V; ID} = -200 \text{ mA; T}_j = 25 \text{ °C} \\ \\ \text{VDS} = -10 \text{ V; ID} = -200 \text{ mA; T}_j = 25 \text{ °C} \\ \\ \text{VDS} = -4.5 \text{ V; T}_j = 25 \text{ °C} \\ \\ \text{VDS} = -4.5 \text{ V; T}_j = 25 \text{ °C} \\ \\ \text{VDS} = -4.5 \text{ V; T}_j = 25 \text{ °C} \\ \\ \text{VDS} = -4.5 \text{ V; T}_j = 25 \text{ °C} \\ \\ \text{VDS} = -4.5 \text{ V; T}_j = 25 \text{ °C} \\ \\ \text{VDS} = -4.5 \text{ V; T}_j = 25 \text{ °C} \\ \\ \text{VDS} = -200 \text{ mA; T}_j = 25 \text{ °C} \\ \\ \text{VDS} = -200 \text{ mA; T}_j = 25 \text{ °C} \\ \\ \text{VDS} = -200 \text{ mA; T}_j = 25 \text{ °C} \\ \\ \text{VDS} = -200 \text{ mA; T}_j = 25 \text{ °C} \\ \\ \text{VDS} = -200 \text{ mA; T}_j = 25 \text{ °C} \\ \\ \text{VDS} = -200 \text{ mA; T}_j = 25 \text{ °C} \\ \\ \text{VDS} = -200 \text{ mA; T}_j = 25 \text{ °C} \\ \\ \text{VDS} = -200 \text{ mA; T}_j = 25 \text{ °C} \\ \\ \text{VDS} = -200 \text{ mA; T}_j = 25 \text{ °C} \\ \\ \text{VDS} = -200 \text{ mA; T}_j = 25 \text{ °C} \\ \\ \text{VDS} = -200 \text{ mA; T}_j = 25 \text{ °C} \\ \\ \text{VDS} = -200 \text{ mA; T}_j = 25 \text{ °C} \\ \\ \text{VDS} = -200 \text{ mA; T}_j = 25 \text{ °C} \\ \\ \text{VDS} = -200 \text{ mA; T}_j = 25 \text{ °C} \\ \\ \text{VDS} = -200  mA; T$		drain-source breakdown voltage         I <sub>D</sub> = -250 μA; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 25 °C         -30	

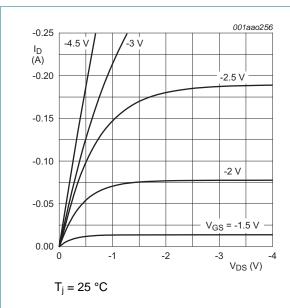
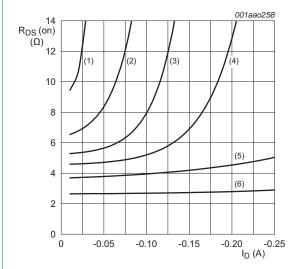


Fig 7. Output characteristics: drain current as a function of drain-source voltage; typical values



T<sub>j</sub> = 25 °C

(1)  $V_{GS} = -1.75 \text{ V}$ 

(2)  $V_{GS} = -2.0 \text{ V}$ 

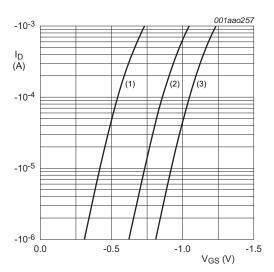
(3)  $V_{GS} = -2.25 \text{ V}$ 

(4)  $V_{GS} = -2.5 \text{ V}$ 

(5)  $V_{GS} = -3.0 \text{ V}$ 

(6)  $V_{GS} = -4.5 \text{ V}$ 

Fig 9. Drain-source on-state resistance as a function of drain current; typical values



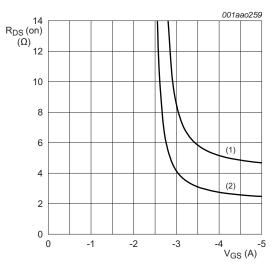
 $T_i = 25 \, ^{\circ}C; \, V_{DS} = -5 \, V$ 

(1) minimum values

(2) typical values

(3) maximum values

Fig 8. Subthreshold drain current as a function of gate-source voltage

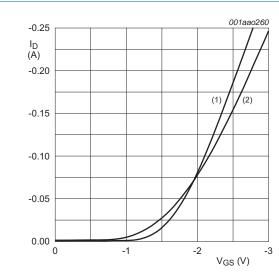


 $I_D = -200 \text{ mA}$ 

(1)  $T_i = 150 \, ^{\circ}C$ 

(2)  $T_j = 25 \, ^{\circ}\text{C}$ 

Fig 10. Drain-source on-state resistance as a function of gate-source voltage; typical values

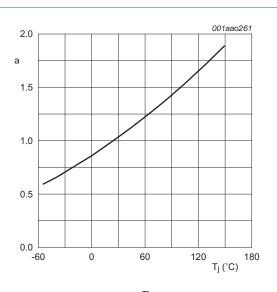


 $V_{DS} > I_D \times R_{DSon}$ 

(1) 
$$T_j = 25 \, ^{\circ}C$$

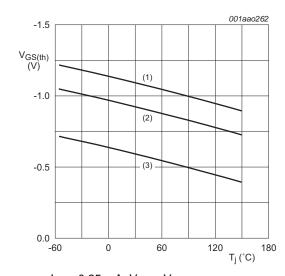
(2) 
$$T_i = 150 \, ^{\circ}\text{C}$$

Fig 11. Transfer characteristics: drain current as a function of gate-source voltage; typical values



$$a = \frac{R_{DSon}}{R_{DSon(25^{\circ}C)}}$$

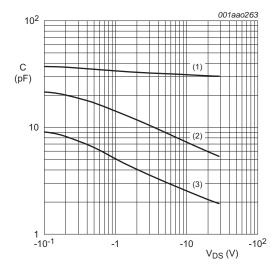
Fig 12. Normalized drain-source on-state resistance as a function of junction temperature; typical values



 $I_D$  = -0.25 mA;  $V_{DS}$  =  $V_{GS}$ 

- (1) maximum values
- (2) typical values
- (3) minimum values

Fig 13. Gate-source threshold voltage as a function of junction temperature



 $f = 1 MHz; V_{GS} = 0 V$ 

- (1) C<sub>iss</sub>
- (2) C<sub>oss</sub>
- (3) C<sub>rss</sub>

Fig 14. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values

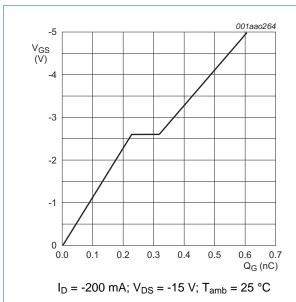


Fig 15. Gate-source voltage as a function of gate charge; typical values

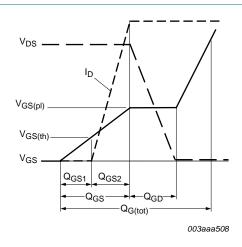
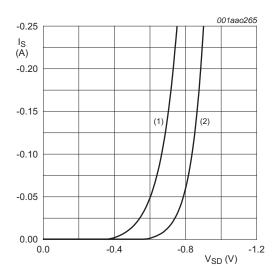


Fig 16. Gate charge waveform definitions



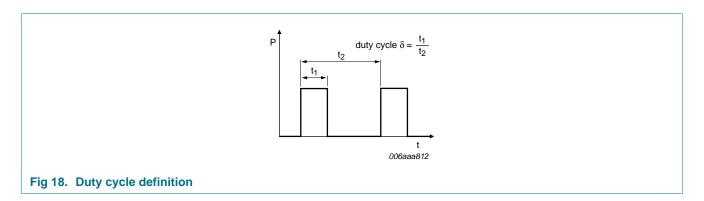
 $V_{GS} = 0 V$ 

(1)  $T_i = 150 \, ^{\circ}\text{C}$ 

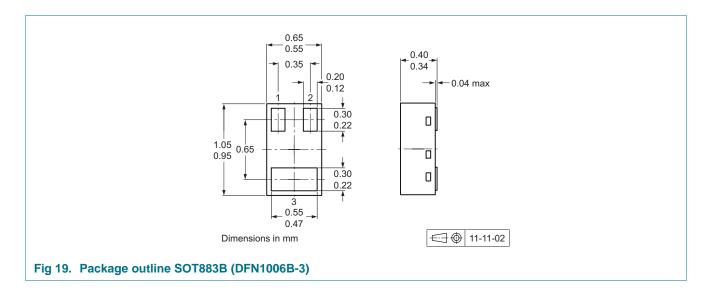
(2)  $T_j = 25 \, ^{\circ}C$ 

Fig 17. Source current as a function of source-drain voltage; typical values

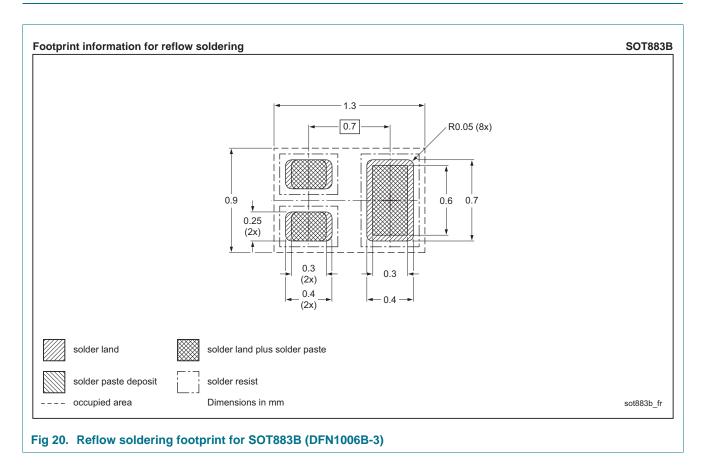
### 8. Test information



### 9. Package outline



### 10. Soldering



NX3008PBKMB

30 V, single P-channel Trench MOSFET

## 11. Revision history

### Table 8. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
NX3008PBKMB v.1	20120511	Product data sheet	-	-

### 12. Legal information

#### 12.1 Data sheet status

Document status[1] [2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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product for such automotive applications, use and specifications, and (b) whenever customer uses the product for automotive applications beyond Nexperia's specifications such use shall be solely at customer's own risk, and (c) customer fully indemnifies Nexperia for any liability, damages or failed product claims resulting from customer design and use of the product for automotive applications beyond Nexperia's standard warranty and Nexperia's product specifications.

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#### 12.4 Trademarks

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### 13. Contact information

For more information, please visit:http://www.nexperia.com

For sales office addresses, please send an email to:salesaddresses@nexperia.com

### **Nexperia**

# NX3008PBKMB

30 V, single P-channel Trench MOSFET

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